

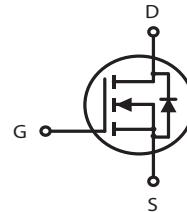


## N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
VDSS	ID	R <sub>DS(ON)</sub> (mΩ) Max
30V	28A	23 @ V <sub>GS</sub> = 10V
		39 @ V <sub>GS</sub> = 4.5V

## FEATURES

- Super high dense cell design for low R<sub>DS(ON)</sub>.
- Rugged and reliable.
- TO-252 and TO-251 Package.

STU SERIES  
TO-252AA(D-PAK)STD SERIES  
TO-251(I-PAK)ABSOLUTE MAXIMUM RATINGS (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous @ T <sub>J</sub> =125°C -Pulsed <sup>a</sup>	I <sub>D</sub>	28	A
	I <sub>DM</sub>	70	A
Drain-Source Diode Forward Current	I <sub>S</sub>	20	A
Maximum Power Dissipation @ T <sub>c</sub> =25°C	P <sub>D</sub>	50	W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 175	°C

## THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	3	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	50	°C/W

# STU/D20N03L

ELECTRICAL CHARACTERISTICS (T<sub>C</sub>=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V			1	μA
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V			±100	nA
<b>ON CHARACTERISTICS</b> <sup>a</sup>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.5	2.5	V
Drain-Source On-State Resistance	R <sub>D(S)ON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A		17	23	m ohm
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A		30	39	m ohm
On-State Drain Current	I <sub>D(ON)</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =10V	50			A
Forward Transconductance	g <sub>F</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =20A		8		S
<b>DYNAMIC CHARACTERISTICS</b> <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V f=1.0MHz		614		pF
Output Capacitance	C <sub>oss</sub>			83		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			61		pF
<b>SWITCHING CHARACTERISTICS</b> <sup>b</sup>						
Turn-On Delay Time	t <sub>D(ON)</sub>	V <sub>DD</sub> =15V I <sub>D</sub> =1A V <sub>GS</sub> =10V R <sub>L</sub> =15 ohm R <sub>GEN</sub> =11 ohm		15.2		ns
Rise Time	t			4.5		ns
Turn-Off Delay Time	t <sub>D(OFF)</sub>			23.3		ns
Fall time	t			12.7		ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DD</sub> =15V, I <sub>D</sub> =1A, V <sub>GS</sub> =10V		17.8		nC
		V <sub>DS</sub> =15V, I <sub>D</sub> =1A, V <sub>GS</sub> =4.5V		8.8		nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DD</sub> =15V, I <sub>D</sub> =1A R <sub>L</sub> =15 ohm		2.8		nC
Gate-Drain Charge	Q <sub>gd</sub>			2		nC

# STU/D20N03L

ELECTRICAL CHARACTERISTICS ( $T_c=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS <sup>a</sup>						
Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{V}, I_s = 20\text{A}$		1	1.3	V

## Notes

a.Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

b.Guaranteed by design, not subject to production testing.

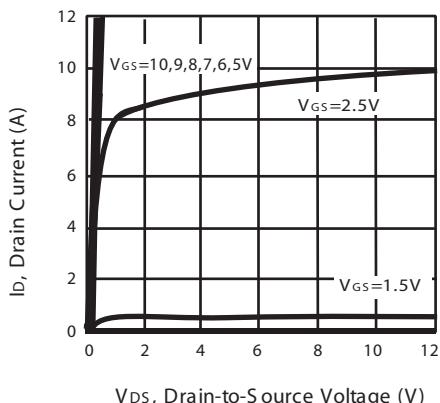


Figure 1. Output Characteristics

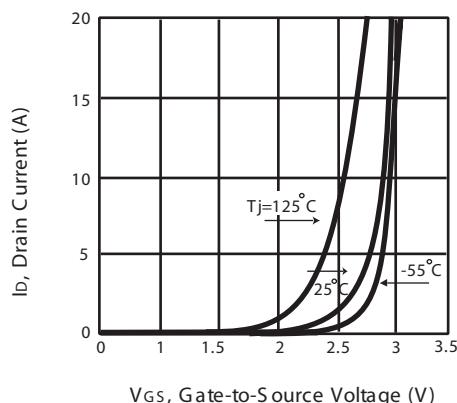


Figure 2. Transfer Characteristics

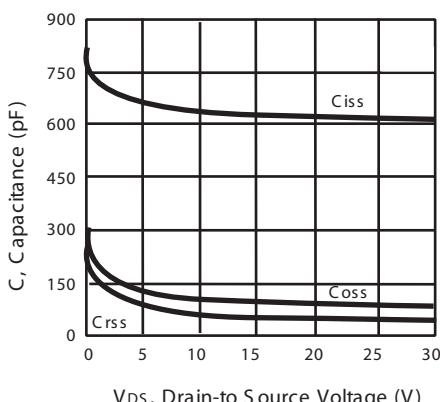


Figure 3. Capacitance

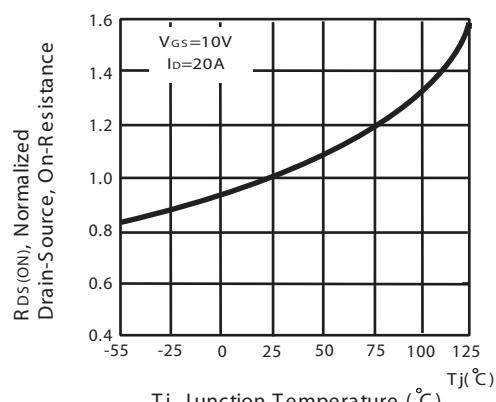
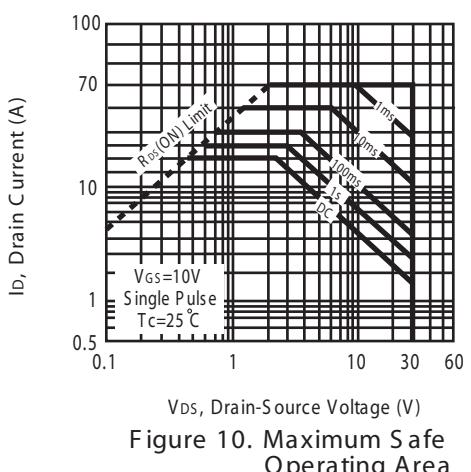
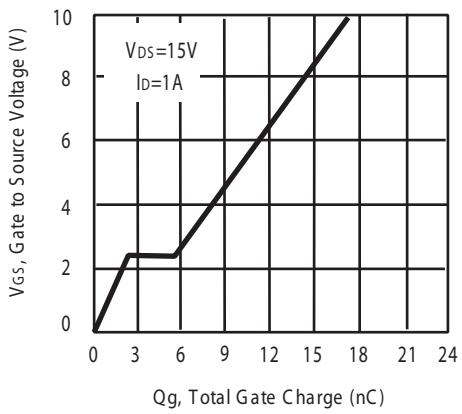
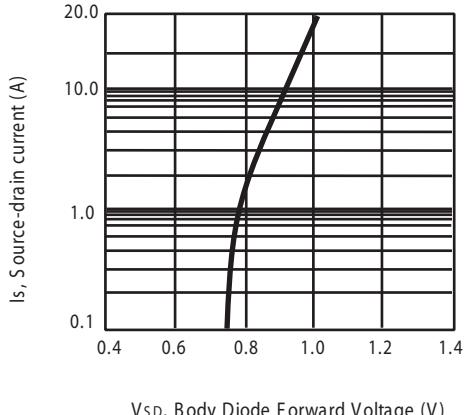
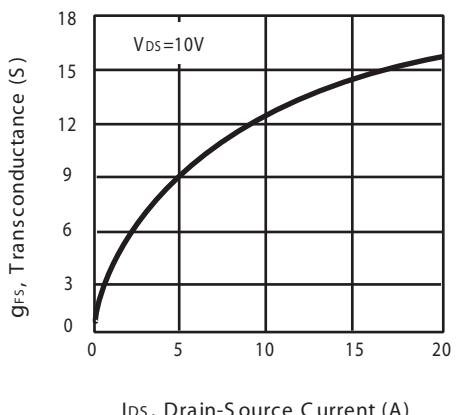
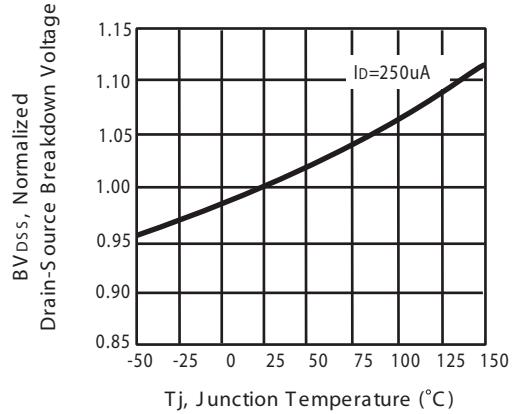
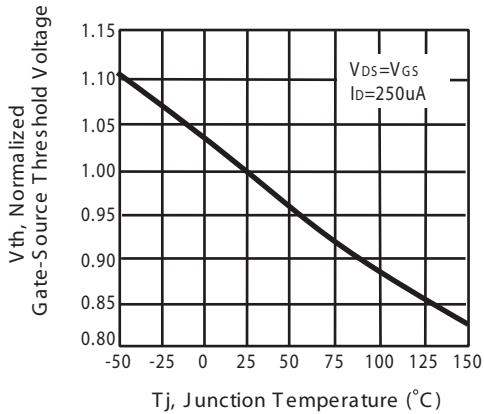


Figure 4. On-Resistance Variation with Drain Current and Temperature

# STU/D20N03L



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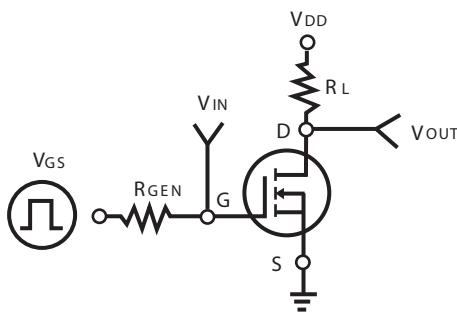


Figure 11. S switching Test Circuit

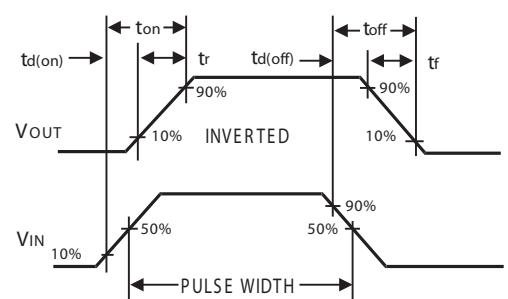


Figure 12. S switching Waveforms

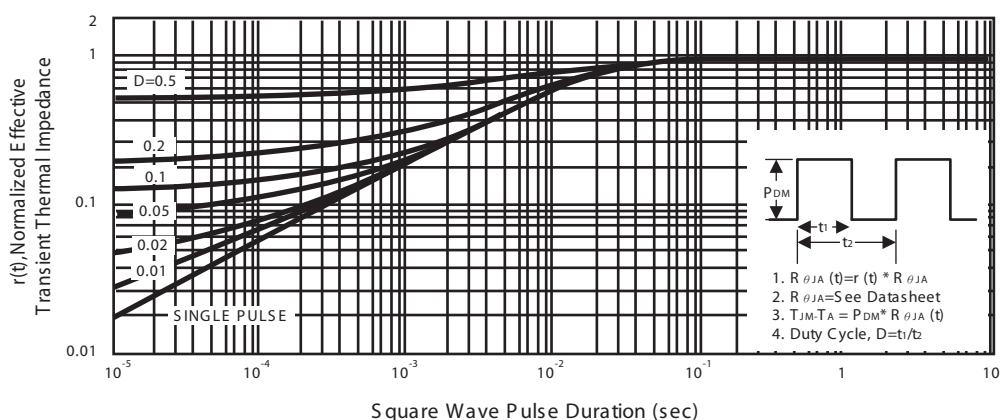


Figure 13. Normalized Thermal Transient Impedance Curve





